



3-terminal Regulator & LDO Regulator series

# Standard Variable **Output LDO Regulator**



### **BA00DD0W** and **BA00CC0W** Series

### General Description

The BA00DD0/CC0 series are low-saturation regulators available for outputs up to 2A/1A. The output voltage can be arbitrarily configured using the external resistance. These series of LDO regulators are offered in a broad packaging lineup. This IC has a built-in over-current protection circuit that prevents the destruction of the IC due to output short circuits and a thermal shutdown circuit that protects the IC from thermal damage due to overloading.

### Features

- 1) Maximum output current: 2A (BA00DD0 series), 1A(BA00CC0 series)
- 2)  $\pm$  1% high-precision output voltage (BA00DD0)
- 3) Low saturation with PNP output
- 4) Built-in over-current protection circuit that prevents the destruction of the IC due to output short circuits
- 5) Built-in thermal shutdown circuit for protecting the IC from thermal damage due to overloading
- 6) Built-in over- voltage protection circuit that prevents the destruction of the IC due to power supply surges
- 7) TO220CP and HRP5 packaging(BA00DD0), and TO220FP/CP and TO252 packaging(BA00CC0)

### Applications

Usable in DSP power supplies for DVDs and CDs, FPDs, televisions, personal computers or any other consumer device

### Line up

### 1A BA00CC0 Series

Part Number	Package
BA00CC0WT	TO220FP-5
BA00CC0WT-V5	TO220FP-5(V5)
BA00CC0CP-V5	TO220CP-V5
BA00CC0WFP	TO252-5

### 2A BA00DD0 Series

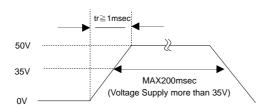
Part Number	Package				
BA00DD0CP-V5	TO220CP-V5				
BA00DD0WHFP	HRP-5				

### ●ABSOLUTE MAXIMUM RATINGS(Ta=25°C)

Parameter	Symbol	Limits	Unit
Input Power Supply Voltage*1	Vcc	-0.3 ~ +35	V
		2300(HRP5)	
Power Dissipation *2	Pd	1300(TO252-5)	mW
		2000(TO220FP/CP)	
Operating Temperature Range	Topr	-40 ~ +125	ပ္
Ambient Storage Temperature	Tstg	-55 ~ +150	ပ္
Junction Temperature	Tjmax	+150	ပ္
Output Control Terminal Voltage	VCTL	-0.3 ~ +Vcc	V
Voltage Applied to the Tip *3	Vcc peak	+50	V

<sup>\*1</sup> Must not exceed Pd

<sup>\*3</sup> Applied voltage : 200msec or less (tr≥1msec)



### Recommended Operating Range (Ta=25°C)

Parameter		Symbol	Min.	Max.	Unit	
Input Power	BA00CC0	Cymbol	4.0	25.0	OTIL	
'		Vcc	_		V	
Supply Voltage	BA00DD0□□		3.0	25.0		
Output Current	BA00CC0□□	lo		1	Α	
Output Ourient	BA00DD0□□	2	_	2		
Output Control Terminal Voltage		VCTL	0	Vcc	V	

### Electrical Characteristics(ABRIDGED)

 $BA00CC0 \ \square \ \ Series \ (unless \ specified \ otherwise, \ Ta=25^{\circ}\!C, \ Vcc=10V, \ VcTL=5V, \ Io=500mA, \ R_1=2.2K\Omega, \ R_2=6.8K\Omega)$ 

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
C-terminal Voltage	Vc	1.200	1.225	1.250	V	Io=50mA
Circuit Current at the Time of Shutdown	Isd	ı	0	10	μΑ	VCTL=0V
Minimum I/O Voltage Difference	ΔVd	ı	0.3	0.5	V	Vcc= 0.95×Vo
Output Current Capacity	lo	1.0	_	ı	Α	
Input Stability	Reg.I	ı	20	100	mV	Vcc= 6V→25 V
Load Stability	Reg.L	ı	50	150	mV	lo=5mA→1A
Output Voltage Temperature Coefficient*	Tcvo	-	±0.02		%/℃	lo=5mA ,Tj=0~125℃

<sup>\*</sup>Design guarantee(100% shipping inspection not performed)

 $BA00DD0 \square \square \ \ Series \ (unless \ specified \ otherwise, \ Ta=25^{\circ}\!C, \ Vcc=8V, \ VcTL=3V, \ Io=500mA, \ R_1=15K\Omega, \ R_2=44K\Omega)$ 

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
C-terminal Voltage	VADJ	1.257	1.270	1.283	V	lo=100mA	
Circuit Current at the Time of Shutdown	Isd	_	0	10	μΑ	VCTL=0V	
Minimum I/O Voltage Difference	ΔVd	_	0.45	0.7	V	Vcc= 0.95×Vo, lo=2A	
Output Current Capacity	lo	2.0	_	ı	Α		
Input Stability	Reg.I	_	15	35	mV	Vcc= $5.7V \rightarrow 25 V$ , Io=200mA	
Load Stability	Reg.L	_	50	100	mV	lo=0mA→2A	
Output Voltage Temperature Coefficient*	Tcvo	_	±0.02		%/℃	lo=5mA ,Tj=0~125°C	

<sup>\*</sup>Design guarantee(100% shipping inspection not performed)

<sup>\*1</sup> Must not exceed Fd

\*2 HRP5 : In cases in which Ta≥25°C when a 70mm×70mm×1.6mm glass epoxy board is used, the power is reduced by 18.4 mW/°C.

TO252-5 : In cases in which Ta≥25°C when a 70mm×70mm×1.6mm glass epoxy board is used, the power is reduced by 10.4 mW/°C. TO252FP-5 : No heat sink. When Ta≥25°C, the power is reduced by 16 mW/°C.

#### BA00CC0 □ □ (3.3V preset voltage) (Unless specified otherwise, Vcc=10V, Vout=3.3V preset, VctL=3V, Io=0mA, R1=2.2KΩ, and R2=6.8KΩ) 3.0 2.5 OUTPUT VOLTAGE:VOUT[V] CIRCUIT CURRENT:ICC[mA] OUTPUT VOLTAGE:VOUTIVI 1.0 1.0 1.0 0.5 0.0 10 12 16 14 0 2 10 12 14 18 2 10 12 14 SUPPLY VOLTAGE:VCC[V] SUPPLY VOLTAGE:VCC[V] SUPPLY VOLTAGE:VCC[V] Fig.1 Circuit current Fig.2 Input Stability Fig.3 Input Stability (Io=500mA) 600 3.5 3.0 DROPOUT VOLTAGE ☆ Vd[mV] OUTPUT VOLTAGE: VOUTIV RIPPLE REJECTION: R. RIGB 2.5 400 1111111 300 40 1.5 200 1.0 20 100 0.5 0.0 100 100k 10k 0 200 400 600 800 1000 1200 1400 1600 1800 2000 100 200 300 400 500 600 700 800 900 1000 FREQUENCY:f[Hz] OUTPUT CURRENT:lo[mA] OUTPUT CURRENT:lo[mA] Fig.5 Input/Output Voltage Difference Fig.6 Ripple Rejection Characteristics Fig.4 Load Stability Io- Δ Vd Characteristics (Vcc=2.95V) (Io=100mA) 4.5 200 900 CONTROL CURRENT:ICTL[µA] 4.0 800 OUTPUT VOLTAGE:VOUTIV CIRCUIT CURRENT:lcc[mA] 150 700 3.5 600 100 500 400 300 50 200 100 2.0 -20 -40 40 60 10 12 100 200 300 400 500 600 700 CONTROL VOLTAGE:VCTL[V] AMBIENT TEMPERATURE:Ta[°C] OUTPUT CURRENT:lo[mA] Fig.7 Output Voltage Fig.8 Circuit Current by load Level Fig.9 CTL Voltage vs. CTL Current **Temperature Characteristics** $(IOUT=0mA\rightarrow 1A)$ OUTPUT VOLTAGE:VOUT[V] OUTPUT VOLTAGE: VOUTIVI OUTPUT VOLTAGE:VOUT[V 130 140 150 160 170 190 180 CONTROL VOLTAGE:VCTL[V] SUPPLY VOLTAGE:Vcc[V] AMBIENT TEMPERATURE:Ta[°C] Fig.10 CTL Voltage vs. Output Voltage Fig.11 Overvoltage Operating Fig.12 Thermal Shutdown Characteristics(Io=200mA) Circuit Characteristics

Reference Data

### Reference Data BA00DD0 □ □ (5.0V preset voltage) (Unless specified otherwise, Vcc=8V, VouT=5V preset, VcTL=3V, Io=0mA, R1=15KΩ, and R2=44KΩ) 5.5 5.0 CIRCUIT CURRENT:ICC[mA] OUTPUT VOLTAGE:VOUT[V] OUTPUT VOLTAGE:VOUT[V] 4.5 4.0 3.5 3.0 2.5 2.0 0.5 0.0 10 12 14 16 18 10 12 14 SUPPLY VOLTAGE:VCC[V] SUPPLY VOLTAGE:VCC[V] SUPPLY VOLTAGE:VCC[V] Fig.13 Circuit Current Fig.14 Input Stability Fig.15 Input Stability (lo=2A) 55 RIPPLE REJECTION:R.R[dB] 45 600 OUTPUT VOLTAGE:VOUT[V] 40 500 35 400 25 300 20 15 200 10 100 FREQUENCY:f[Hz] OUTPUT CURRENT:IOUT[A] Fig.16 Load Stability Fig.17 Input/Output Voltage Difference Fig.18 Ripple Rejection Characteristics (Iout=100mA) Iout- Δ Vd Characteristics (Vcc=4.75V) 5.2 200 180 700 160 OUTPUT VOLTAGE:VOUT[V] CONTROL CURRENT:ICTL[µA] 600 140 CIRCUIT CURRENT:[mA] 120 100 400 80 300 60 200 40 100 20 6 8 10 12 14 16 18 20 CONTROL VOLTAGE:VCTL[V] -20 60 80 -40 OUTPUT CURRENT:IOUT[A] AMBIENT TEMPERATURE:Ta[°C] Fig.19 Output Voltage Fig.20 Circuit Current by load Level Fig.21 CTL Voltage vs. CTL Current **Temperature Characteristics** (Iout=0mA→2A) OUTPUT VOLTAGE: VOUT[V] OUTPUT VOLTAGE: VOUTIV OUTPUT VOLTAGE: VOUTIV 3

Fig.22 CTL Voltage vs. Output Voltage

CONTROL VOLTAGE:VCTL[V]

12 14 16 18 20

Fig.23 Overvoltage Operating Characteristics(Io=200mA)

20

SUPPLY VOLTAGE:Vcc[V]

30

Fig.24 Thermal Shutdown Circuit Characteristics

170

180

190

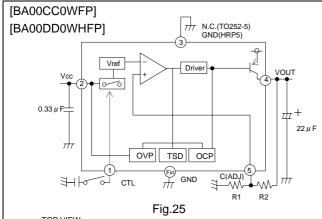
160

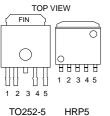
AMBIENT TEMPERATURE:Ta[°C]

150

130

### Block Diagrams





PINNo.	Symbol	Function	
1	CTL	Output voltage ON/OFF control	
2	VCC	Power supply voltage input	
3	N.C./GND	Unconnected terminal/GND*	
4	OUT	Voltage output	
5	С	Output voltage regulation terminal	
FIN	GND	GND	

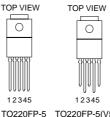
\*TO252-5 is N.C., and HRP5 is GND

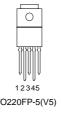
## [BA00CC0WT] [BA00DD0WT] 0.33 μ F 22 μ F OVP TSD OCP

GND

Fig.26 TOP VIEW

CTL





PINNo. Symbol Function CTL Output voltage ON/OFF control 2 VCC Power supply voltage input 3 GND GND OUT 4 Voltage output 5 ADJ Output voltage regulation terminal

R1

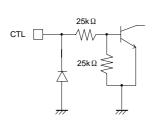
R2

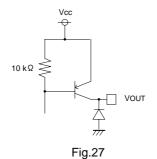
T<u>O220F</u>P-5 TO220FP-5(V5) 0

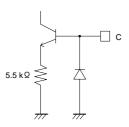
## TO220CP-V5

### ●Input / Output Equivalent Circuit Diagrams

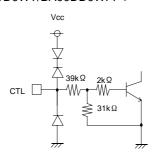
### < BA00CC0WT/BA00CC0WFP >

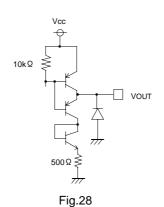


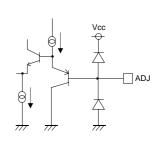




### < BA00DD0WT/BA00DD0WFP >







### Output Voltage Configuration Method

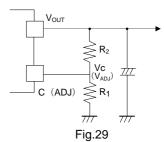
Please connect resistors R1 and R2 (which determines the output voltage) as shown in Fig.29.

Please be aware that the offset due to the current that flows from the ADJ terminal becomes large when resistors with large

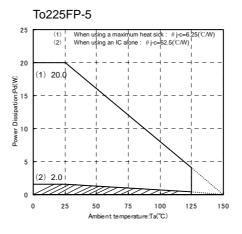
values are used. The use of resistors with R<sub>1</sub>=2K $\Omega$  to 15 K $\Omega$  is recommended.

Vo = Vc (VADJ) 
$$\times \left[1 + \frac{R_2}{R_1}\right]$$

BA 🗆 CC0 🗆 🗆 Vc: 1.225 (Typ.)  $BA \square \square DD0 \square \square$ VADJ: 1.270 (Typ.)



### Thermal Design



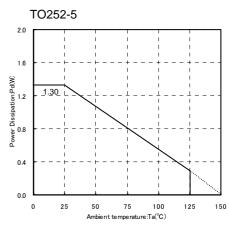


Fig.30

Fig.31 Fig.

When using at temperatures over Ta=25°C, please refer to the heat reducing characteristics shown in Fig.30 through 32. The IC characteristics are closely related to the temperature at which the IC is used, so it is necessary to operate the IC at temperatures less than the maximum junction temperature TjMAX.

Fig.31 shows the acceptable loss and heat reducing characteristics of the TO220FP package The portion shown by the diagonal line is the acceptable loss range that can be used with the IC alone. Even when the ambient temperature Ta is a normal temperature (25°C), the chip (junction) temperature Tj may be quite high so please operate the IC at temperatures less than the acceptable loss Pd.

The calculation method for power consumption Pc(W) is as follows:

 $Pc = (Vcc-Vo) \times Io + Vcc \times Icca$ Acceptable loss  $Pd \leq Pc$  Vcc : Input voltage
Vo : Output voltage
Io : Load current
Icca : Circuit current

Solving this for load current IO in order to operate within the acceptable loss,

$$lo \le \frac{Pd - Vcc \times lcca}{Vcc - Vo}$$

(Please refer to Figs.8 and 20 for Icca.)

It is then possible to find the maximum load current IoMAX with respect to the applied voltage Vcc at the time of thermal design.

Calculation Example

Example 1) When Ta=85°C, Vcc=8.3V, Vo=3.3V, BA33DD0WT

 $\begin{array}{l} \text{Io} \leqq \frac{1.04 - 8.3 \times \text{Icca}}{5} \\ \text{Io} \leqq 200 \text{mA (Icca : 2mA)} \end{array} \qquad \left( \begin{array}{c} \text{With the IC alone : } \theta \text{ ja=62.5°C/W} \rightarrow \text{-16mW/°C} \\ 25 \text{°C=2000mW} \rightarrow 85 \text{°C=1040mW} \end{array} \right)$ 

Please refer to the above information and keep thermal designs within the scope of acceptable loss for all operating temperature ranges. The power consumption Pc of the IC when there is a short circuit (short between Vo and GND) is :

Pc=Vcc×(Icca+Ishort)

Ishort: Short circuit current

### Terminal Vicinity Settings and Cautions

Vcc Terminal

Please attach a capacitor (greater than 0.33  $\mu$  F) between the Vcc and GND.

The capacitance values differ depending on the application, so please chose a capacitor with sufficient margin and verify the operation on an actual board.

CTL Terminal

The CTL terminal is turned ON at 2.0V and higher and OFF at 0.8V and lower within the operating power supply voltage range.

The power supply and the CTL terminal may be started up and shut down in any order without problems.

### ■Vo Terminal

Please attach an anti-oscillation capacitor between VouT and GND. The capacitance of the capacitor may significantly change due to factors such as temperature changes, which may cause oscillations. Please use a tantalum capacitor or aluminum electrolytic capacitor with favorable characteristics and small external series resistance (ESR) even at low temperatures. The output oscillates regardless of whether the ESR is large or small. Please use the IC within the stable operating region while referring to the ESR characteristics reference data shown in Figs.33 through 35. In cases where there are sudden load fluctuations, the a large capacitor is recommended.

Below figure , it is ESR-to-lo stability Area characteristics , measured by  $22 \,\mu$  F -ceramic-capacitor and resistor connected in series

This characteristics is not equal value perfectly to  $22\,\mu$  F-aluminum electrolytic capacitor in order to measurement method.

Note, however, that the stable range suggested in the figure depends on the IC and the resistance load involved, and can vary with the board's wiring impedance, input impedance, and/or load impedance. Therefore, be certain to ascertain the final status of these items for actual use.

Keep capacitor capacitance within a range of  $22 \,\mu\,\text{F} \sim 1000 \,\mu\,\text{F}$ . It is also recommended that a  $0.33 \,\mu\,\text{F}$  bypass capacitor be connected as close to the input pin-GND as location possible. However, in situations such as rapid fluctuation of the input voltage or the load, please check the operation in real application to determine proper capacitance.

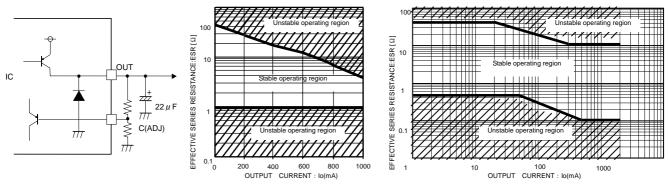


Fig.33:Output equivalent circuit

Fig.34:lo vs. ESR characteristics  $(BA \square \square CC0,22 \mu F)$ 

Fig.35: lo vs. ESR characteristics (BA $\square$ DD0,22 $\mu$ F)

### ●Other

### 1) Protection Circuits

Overcurrent Protection Circuit

A built-in overcurrent protection circuit corresponding to the current capacity prevents the destruction of the IC when there are load shorts. This protection circuit is a "7"-shaped current control circuit that is designed such that the current is restricted and does not latch even when a large current momentarily flows through the system with a high-capacitance capacitor. However, while this protection circuit is effective for the prevention of destruction due to unexpected accidents, it is not suitable for continuous operation or transient use. Please be aware when creating thermal designs that the overcurrent protection circuit has negative current capacity characteristics with regard to temperature (Refer to Figs.4 and 16).

### Thermal Shutdown Circuit (Thermal Protection)

This system has a built-in temperature protection circuit for the purpose of protecting the IC from thermal damage. As shown above, this must be used within the range of acceptable loss, but if the acceptable loss happens to be continuously exceeded, the chip temperature Tj increases, causing the temperature protection circuit to operate.

When the thermal shutdown circuit operates, the operation of the circuit is suspended. The circuit resumes operation immediately after the chip temperature Tj decreases, so the output repeats the ON and OFF states (Please refer to Figs.12 and 24 for the temperatures at which the temperature protection circuit operates).

There are cases in which the IC is destroyed due to thermal runaway when it is left in the overloaded state. Be sure to avoid leaving the IC in the overloaded state.

### Reverse Current

In order to prevent the destruction of the IC when a reverse current flows through the IC, it is recommended that a diode be placed between the Vcc and Vo and a pathway be created so that the current can escape (Refer to Fig.36).

2) This IC is bipolar IC that has a P-board (substrate) and P+ isolation layer between each devise, as shown in Fig.37. A P-N junction is formed between this P-layer and the N-layer of each device, and the P-N junction operates as a parasitic diode when the electric potential relationship is GND> Terminal A, GND> Terminal B, while it operates as a parasitic transistor when the electric potential relationship is Terminal B GND> Terminal A. Parasitic devices are intrinsic to the IC. The operation of parasitic devices induces mutual interference between circuits, causing malfunctions and eventually the destruction of the IC itself. It is necessary to be careful not to use the IC in ways that would cause parasitic elements to operate. For example, applying a voltage that is lower than the GND (P-board) to the input terminal.

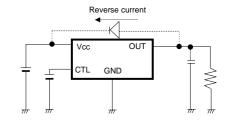
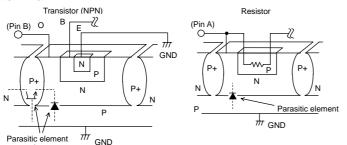


Fig. 36:Bypass diode



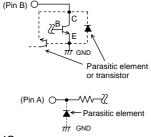


Fig. 37: Example of the basic structure of a bipolar IC

### Part Number Selection







**ROHM** model name Output voltage Current capacity CC0:1A

DD0:1A

Shutdown switch W: With switch None : Without switch

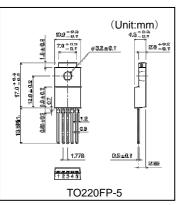
Package T: TÕ220-3,5 F P : TO252-3,5 HFP : HRP5

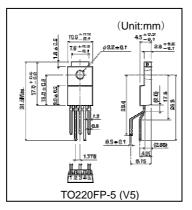
CP: TO220CP

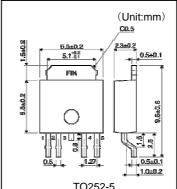
Package specification TR: Embossed taping(HRP5)

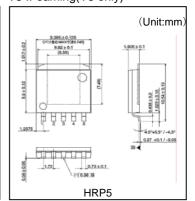
E2: Embossed taping(TO252-5, TO220CP)

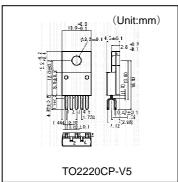
None: Tube container V5 :Foaming(V5 only)





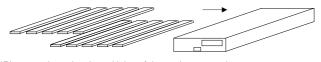








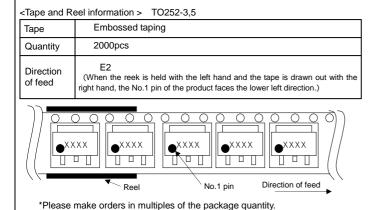
Package Form	Container tube
Package Quantity	500pcs
Package Orientation	The product orientation in each container tube is constant.

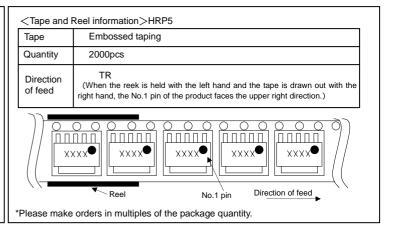


\*Please make orders in multiples of the package quantity.

<Package Specification>TO220FP-5 (V5) Package Form Container tube Package Quantity 500pcs The product orientation in each container Package Orientation tube is constant.

\*Please make orders in multiples of the package quantity.





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